

## Product End-of-Life Disassembly Instructions

**Product Category: Monitors and Displays** 

**Marketing Name / Model** 

[List multiple models if applicable.]

HP ProDisplay P19A 19-inch LED Backlit Monitor

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

- 1.1 Items listed below are classified as requiring selective treatment.
- 1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1
External electrical cables and cords	VGA cable*1, Power cord*1 All are inside monitor carton box	2
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing		0

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refractory ceramic fibers	
Components, parts and materials containing radioactive substances	0

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	
Hexagon Screw Driver	
Flathead screwdriver	

## 3.0 Product Disassembly Process

- 3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:
- 1. Separate base and column by hand, then use tool to separate monitor head and stand.
- 2. Use tool to separate screw from rear cover, then separate rear cover from monitor head by hand.
- 3. Tear the tape from lamp wire and LVDS FFC, then disassemble the lamp wire, LVDS FFC and ctrl-BD FFC from connector, disassemble the chassis from panel.
- Disassemble the ctrl-BD from panel and ctrl-BD, then disassemble ctrl-BD from bezel and separate panel and bezel by hand.
- 5. Separate safety Mylar from chassis, then use tool to release screws on PCBs, tear gaskets from chassis, and separate all connector on PCBs.
- 6. Use tool to separate wall mount plate from rear cover, and separate HP LOGO, button and lens form bezel.
- 7. Use tool to disassemble column rear cover from column, then release the screws to separate hinge from column, and release screws to separate hinge top bracket from hinge.
- 8. Tear the rubber foot from base, then use tool to release screws from base plate, and use tool to separate base plate and base cover.
- 3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Step 1: Separate base and column by hand, then use tool to separate monitor head and stand.



Step 2: Use tool to separate screw from rear cover, then separate rear cover from monitor head by hand.



Step 3: Tear the tape from ctrl-BD wire, then disassemble the ctrl-BD wire, Separate panel and the bezel.



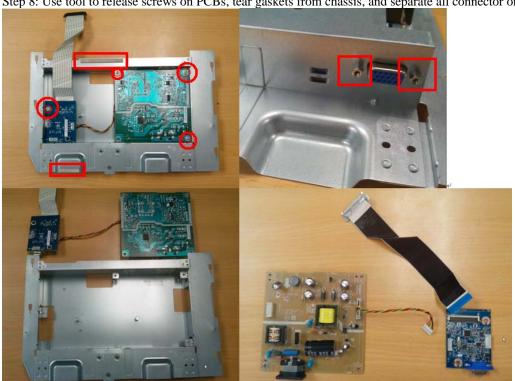
Step 5: Tear the tape from lamp wire and LVDS FFC



Step 6: Release the panel side screws







Step 8: Use tool to release screws on PCBs, tear gaskets from chassis, and separate all connector on PCBs.



Step 9: Use tool to separate wall mount plate from rear cover, and button and lens form bezel.

Step 10: Use tool to disassemble column rear cover from column, then release the screws to separate hinge from column, and release screws to separate hinge top bracket from hinge



Step 11: Tear the rubber foot from base, then use tool to release screws from base plate, and use tool to separate base plate and base cover.

